2SD1138

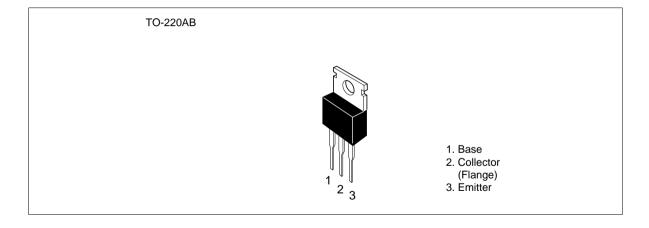
Silicon NPN Triple Diffused

HITACHI

Application

Low frequency high voltage power amplifier TV vertical deflection output complementary pair with 2SB861

Outline





2SD1138

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Rating	Unit
Collector to base voltage	V_{CBO}	200	V
Collector to emitter voltage	V_{CEO}	150	V
Emitter to base voltage	V_{EBO}	6	V
Collector current	I _c	2	А
Collector peak current	I _{C (peak)}	5	А
Collector power dissipation	P _c	1.8	W
	P _c *1	30	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-45 to +150	°C

Note: 1. Value at $T_c = 25$ °C.

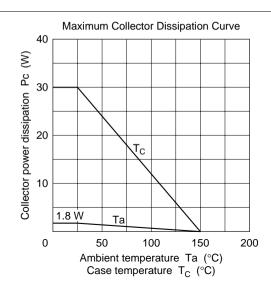
Electrical Characteristics (Ta = 25°C)

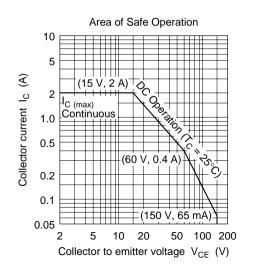
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	150	_	_	V	I_{C} = 50 mA, R_{BE} = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	_	_	V	$I_{\rm E} = 5 \text{ mA}, I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	1	μΑ	V _{CB} = 120 V, I _E = 0
DC current transfer ratio	h _{FE1} *1	60	_	320		$V_{CE} = 4 \text{ V}, I_{C} = 50 \text{ mA}$
	h _{FE2}	60	_	_		$V_{CE} = 10 \text{ V}, I_{C} = 500 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE (sat)}}$	_	_	3.0	V	$I_{\rm C} = 500 \text{ mA}, I_{\rm B} = 50 \text{ mA}^{*2}$
Base to emitter voltage	V_{BE}	_	_	1.0	V	$V_{CB} = 4 \text{ V}, I_{C} = 50 \text{ mA}$
Collector output capacitance	Cob	_	20	_	pF	$V_{CB} = 100 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

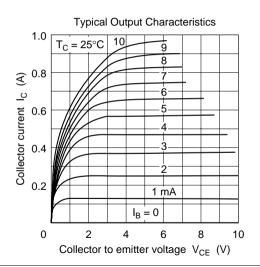
Note: 1. The 2SD1138 is grouped by h_{FE1} as follows.

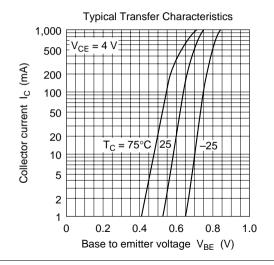
2. Pulse test.

В	С	D	
60 to 120	100 to 200	160 to 320	

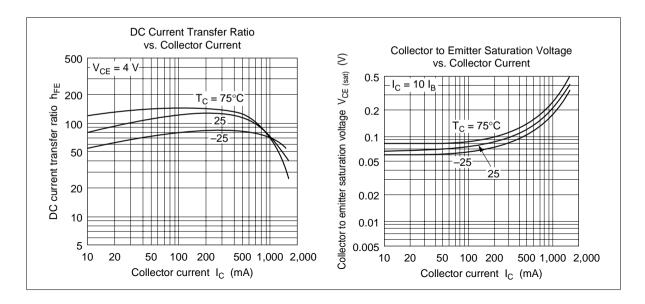




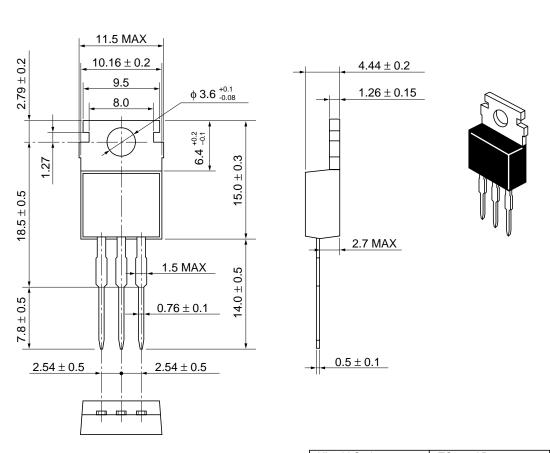




2SD1138



Unit: mm



Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.8 g

Cautions

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